Special Issue

Digital Twins and Cyber-Physical Systems Towards Cybersecurity and Smart Manufacturing

Message from the Guest Editors

This Special Issue serves as a guide for potential authors, clarifying the background and objectives of our focus on Digital Twins (DTs) and Cyber-Physical Systems (CPSs) in enhancing cybersecurity and smart manufacturing, including industrial robotics and mechatronics. Topics of interest include: 1. Fundamentals of DTs and CPSs in smart manufacturing and industrial robotics. 2. Integrating sensors, data analytics, and AI in DTs and CPSs for smart manufacturing and mechatronics. 3. Practical implementation and validation of DTs and CPSs for cybersecurity in manufacturing and robotics. 4. Future applications of DTs and CPSs in cybersecurity, smart manufacturing, and mechatronics. 5. Novel security strategies for DT and CPS frameworks. 6. Other relevant topics related to DTs, CPSs, cybersecurity, and smart manufacturing.

Guest Editors

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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